

To: ALL FIELD

Date: 6/29/2018

Notice Number: OSP20180629B

Subject: PRODUCT CHANGE NOTICE

Renesas is changing the wafer fabrication plant and wafer aperture. From the current Shiga plant with 6 inch wafers to Naka plant or Kawashiri plant with 8 inch wafers. [New wafer shipments will begin in Q3 2019.](#)

PCN#	Release Date dd-mmm-yy	Renesas Part Number	Comments
OSP20180629B	29-Jun-18	PS2502-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2502-4-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2502L-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2502L-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2502L-4-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2503-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2503L-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2503L-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2506-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2506L-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2506L-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2514-1Y-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2514L-1Y-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2514L-1Y-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2514L-1Y-V-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2562-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2562-1-V-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2562L-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2562L-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2562L2-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2702-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2702-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2702-1-V-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2702-1-V-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2706-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2706-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2802-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2802-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2802-4-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2802-4-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2806-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2806-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2806-4-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629B	29-Jun-18	PS2806-4-F3-A	Wafer site change and wafer size change from 6" to 8"

To: CEL Field Sales and Sales Partners

Date: June 29, 2018

Subject: Product Change Notice OSP20180629A

This PCN is to announce a change of the front end wafer fabrication line used to produce the die for the Renesas Photocoupler Detectors supported by CEL.

1. Affected Part Numbers:

Please see the list of part numbers on pages 2 and 3.

2. Description of Changes:

The Front-end wafer fabrication line will be changed as follows;

From (currently): Shiga factory 6-inch Line

To (future) Naka or Kawashiri factory 8-inch Line

There will be no changes to the assembly and testing of any of the products.

All products made with wafers from the Naka or Kawashiri 8" will be specified exactly as those made on the Shiga 6" line. There will not be any changes to the data sheets specifications.

3. Reason of change:

The Shiga plant will be closed.

4. Schedule:

Shipments of products made on the 8-inch line are scheduled to begin in August 2019.

Products made with die from the 6-inch and 8-inch lines will be delivered in parallel for the several months during a transition period, until stock of products made on the 6-inch is depleted.

5. Distinguishing method:

The box label will indicate the new 8 inch products.

There will not be any Part Number changes.

6. Samples:

Samples of the listed P/Ns will be available upon request starting from October 2018.

OSP20180629A	29-Jun-18	PS2802-1-V-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2802-1-V-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2802-4-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2802-4-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2802-4-V-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2802-4-V-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2806-1-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2806-1-F3-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2806-4-A	Wafer site change and wafer size change from 6" to 8"
OSP20180629A	29-Jun-18	PS2806-4-F3-A	Wafer site change and wafer size change from 6" to 8"